

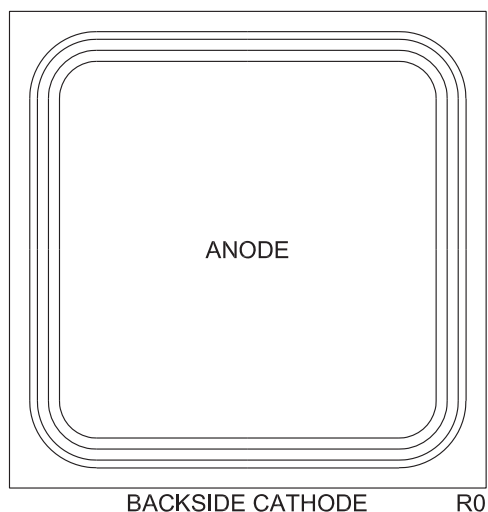
PROCESS CPD107
Schottky Rectifier
3 Amp Schottky Rectifier Chip



PROCESS DETAILS

Die Size	56 x 56 MILS
Die Thickness	11.8 MILS
Anode Bonding Pad Area	51 x 51 MILS
Top Side Metalization	Al - 30,000Å
Back Side Metalization	Ag - 20,000Å

GEOMETRY



GROSS DIE PER 5 INCH WAFER

5,516

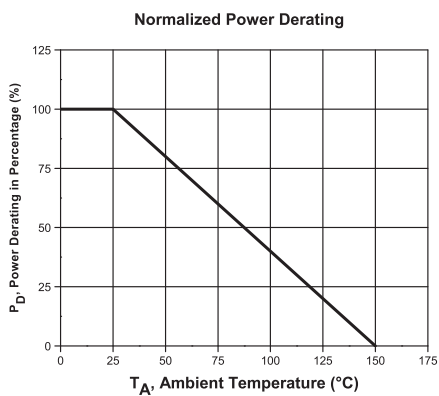
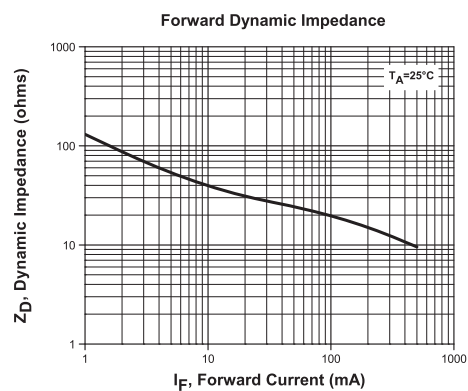
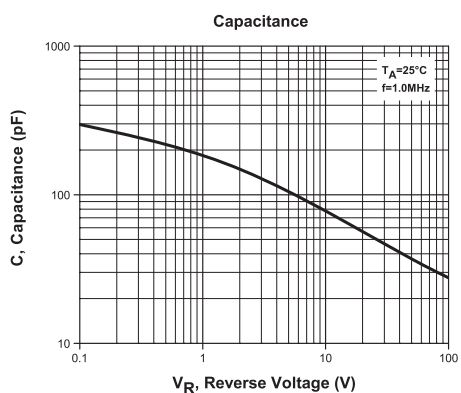
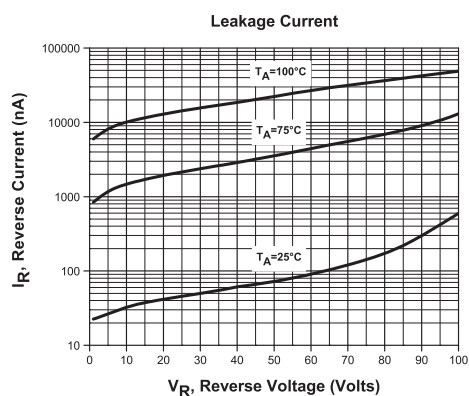
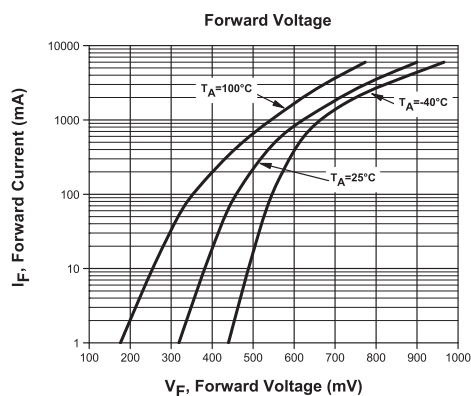
PRINCIPAL DEVICE TYPE

CZSH6-100C

R0 (1-March 2011)

PROCESS CPD107

Typical Electrical Characteristics



R0 (1-March 2011)